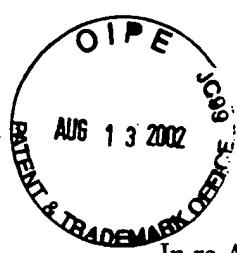


2814



#9C AUT

M. Brunson  
M. BrunsonREC'D 10/28/02  
AUG 22 2002

TECHNOLOGY CENTER 2800

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Todd O. Bolken

§ Group Art Unit: 2814

Serial No.: 09/516,080

§ Examiner: Louie, W.

Filed: March 1, 2000

§

For: EXPOSED DIE MOLDING  
APPARATUS§ Atty Docket: MICS:0043 FLE/MAN  
99-0634Assistant Commissioner  
for Patents  
Washington, D.C. 20231

|                                                                                                                                                                                                                                 |                    |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------|
| CERTIFICATE OF MAILING<br>37 C.F.R. 1.8                                                                                                                                                                                         |                    |
| I hereby certify that this correspondence is being deposited with the U.S.<br>Postal Service as First Class Mail in an envelope addressed to: Assistant<br>Commissioner for Patents, Washington, D.C. 20231, on the date below: |                    |
| August 5, 2002                                                                                                                                                                                                                  | Jennifer Presswood |
| Date                                                                                                                                                                                                                            | Jennifer Presswood |

Sir:

RESPONSE AND AMENDMENT

In response to the Final Official Action mailed on June 5, 2002, Applicant respectfully requests reconsideration of the above-identified application in view of the remarks and amendments set forth below.

entered  
10/28/02  
attorIN THE CLAIMS

Please cancel claim 15 without prejudice.

Please amend claims 1 and 16 as set forth below:

1. (twice amended) A system for molding a circuit package comprising:

a first support plate;